

FlatPAK HC0 Transfer Mold Power Module

Half Bridge - Power MOSFET, 200 A



FEATURES

- Half bridge inverter
- Current sensing and temperature sensing
- Electrically isolated exposed DBC substrate
- C snubber for low EMI
- Qualified according to AQQ324 guidelines
- PPAP capable
- Epoxy compound UL 94 V-0 certified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912


RoHS
COMPLIANT

PRIMARY CHARACTERISTICS

V_{DSS}	80 V
$R_{DS(on)}$, Q1 (chip level)	0.45 m Ω
I_D	195 A at 80 °C
Type	Modules - MOSFET
Package	FlatPAK HC0

ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
MOSFET				
Drain to source voltage	V_{DSS}		80	V
Continuous drain current, V_{GS} at 10 V	I_D	$T_C = 25\text{ °C}$	243	A
		$T_C = 80\text{ °C}$	195	
		$T_C = 118\text{ °C}$	150	
Pulsed drain current	I_{DM}	$T_C = 25\text{ °C}$, $t_p = 250\text{ }\mu\text{s}$, square waveform	1050	
Pulsed source current (body diode)	I_{SM}	$T_C = 150\text{ °C}$, $t_p = 1\text{ ms}$, square waveform	1530	
Power dissipation	P_D	$T_C = 25\text{ °C}$	194	W
Gate to source voltage	V_{GS}		± 20	V
Single pulse avalanche energy	E_{AS}	$T_C = 25\text{ °C}$, $L = 1\text{ mH}$, $V_{GS} = 10\text{ V}$	1800	mJ
Single pulse avalanche current	I_{AS}	$T_C = 25\text{ °C}$, $L = 1\text{ mH}$, $V_{GS} = 10\text{ V}$	60	A
MODULE				
Insulation voltage (RMS)	V_{ISOL}	Any terminal to case, $t = 1\text{ s}$	2000	V

THERMAL- MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction temperature range	T_J		-55	-	175	°C
Storage temperature range	T_{Stg}		-40	-	150	°C
Operating temperature range	T_{op}		-40	-	150	°C
Junction to case MOSFET	R_{thJC}		-	-	0.77	°C/W
Case to heat sink Module	R_{thCS}	Flat, greased surface ⁽¹⁾	-	0.15	-	
Package parasitic stray inductance	L_p		-	10	-	nH
Compression force		Maximum load, test speed: 0.5 mm/min ⁽²⁾	3	-	22	kN
Weight			-	10	-	g
Mounting torque		Mounting screw - M3	-	0.7	-	Nm
Case style			FlatPAK HC0			

Notes

⁽¹⁾ Mounting surface flat, smooth, and greased, $\lambda_{grease} = 4.0\text{ W/mK}$, grease thickness 70 μm

⁽²⁾ Verified by experiment, valid only in certain conditions



ELECTRICAL CHARACTERISTICS (T _J = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Drain to source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	80	-	-	V
		V _{GS} = 0 V, I _D = 5 mA, T _J = -40 °C	80	-	-	
Static drain to source on-resistance, Q1 ⁽¹⁾	R _{DS(on) Q1}	V _{GS} = 10 V, I _D = 200 A	-	0.45	0.91	mΩ
Static drain to source on-resistance, Q2 ⁽¹⁾	R _{DS(on) Q2}	V _{GS} = 10 V, I _D = 200 A	-	0.75	1.21	
Static drain to source on-resistance, Q1	R _{DS(on) Q1}	V _{GS} = 10 V, I _D = 200 A, T _J = 125 °C	-	0.75	-	mΩ
Static drain to source on-resistance, Q2	R _{DS(on) Q2}	V _{GS} = 10 V, I _D = 200 A, T _J = 125 °C	-	1.25	-	
Static drain to source on resistance, Q1 module level ⁽²⁾	R _{DSQ1module}	V _{GS} = 10 V, I _D = 200 A	-	1.79	2.35	mΩ
Static drain to source on resistance, Q2 module level ⁽²⁾	R _{DSQ2module}		-	1.79	2.35	
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.3	2.92	4.0	V
		V _{DS} = V _{GS} , I _D = 250 μA, T _J = -40 °C	-	3.34	-	V
Forward transconductance	g _{fs}	V _{DS} = 20 V, I _D = 200 A, V _{GS} = 10 V	-	333	-	S
Drain to source leakage current	I _{DSS}	V _{DS} = 80 V, V _{GS} = 0 V	-	0.1	1	μA
		V _{DS} = 80 V, V _{GS} = 0 V, T _J = 150 °C	-	50	-	
Internal gate resistance	R _{Gint}		-	1.2	-	Ω
Gate to source leakage	I _{GSS}	V _{GS} = ± 20 V	-	-	± 100	nA
Total gate charge	Q _g	I _D = 80 A, V _{DS} = 48 V, V _{GS} = 0 V / 10 V	-	130	-	nC
Gate to source charge	Q _{gs}		-	39	-	
Gate to drain ("Miller") charge	Q _{gd}		-	24	-	
Turn-on switching energy ⁽³⁾	E _{on}	V _{DD} = 52 V, I _D = 250 A, R _{gon} = 54 Ω, R _{goff} = 81 Ω, V _{GS} = 0 V / 13 V	-	0.42	0.7	mJ
Turn-off switching energy ⁽³⁾	E _{off}		-	2.52	4.0	
Turn-on delay time	t _{d(on)}		-	203	-	ns
Rise time	t _r		-	169	-	
Turn-off delay time	t _{d(off)}		-	1015	-	
Fall time	t _f		-	256	-	
Turn-on switching energy	E _{on}	T _J = 125 °C, V _{DD} = 52 V, I _D = 250 A, R _{gon} = 54 Ω, R _{goff} = 69 Ω, V _{GS} = 0 V / 13 V	-	0.48	-	mJ
Turn-off switching energy	E _{off}		-	2.28	-	
Turn-on delay time	t _{d(on)}		-	186	-	ns
Rise time	t _r		-	175	-	
Turn-off delay time	t _{d(off)}		-	900	-	
Fall time	t _f		-	227	-	
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 40 V, f = 10 kHz	-	11.2	-	nF
Output capacitance	C _{oss}		-	5.6	-	
Reverse transfer capacitance	C _{rss}		-	30	-	pF

Notes

- (1) The difference in R_{DS(on)} values listed in the table refer to the measurement path available inside the module. Q1 and Q2 MOSFETs have the same die size and technology.
- (2) Module level R_{DS(on)} values listed in the table refer to the measurement taken on power terminals. High side MOSFET Q1 was measured on terminals 10 to 12, while low side MOSFET Q2 was measured on terminals 12 to 11.
- (3) Guaranteed by design, not subjected to production test.


SOURCE-DRAIN ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Diode forward voltage	V_{SD}	$I_{SD} = 200\text{ A}$, $V_{GS} = 0\text{ V}$	-	0.83	1	V
Reverse recovery time	t_{rr}	$I_{SD} = 250\text{ A}$, $di/dt = 2400\text{ A}/\mu\text{s}$, $V_R = 52\text{ V}$	-	106	-	ns
Reverse recovery charge	Q_{rr}		-	7180	-	nC
Reverse recovery current	I_{RM}		-	107	-	A
Reverse recovery energy	E_{rec}		-	0.3	-	mJ
Reverse recovery time	t_{rr}	$T_J = 125\text{ }^{\circ}\text{C}$, $I_{SD} = 250\text{ A}$, $di/dt = 2400\text{ A}/\mu\text{s}$, $V_R = 52\text{ V}$	-	100	-	ns
Reverse recovery charge	Q_{rr}		-	6668	-	nC
Reverse recovery current	I_{RM}		-	107	-	A
Reverse recovery energy	E_{rec}		-	0.263	-	mJ

INTERNAL NTC - THERMISTOR SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUE	UNITS
Resistance	R_{25}	$T = 25\text{ }^{\circ}\text{C}$	10 000	Ω
B-value	$B_{25/100}$	$R_2 = R_{25} \exp. [B_{25/100}(1/T_2 - 1/(298.15\text{ K}))]$	$3625 \pm 1\%$	K
Operating temperature range at zero power			-40 to +150	$^{\circ}\text{C}$
Dissipation factor D			3.0	mW/K
Thermal time constant τ			< 4	s

INTERNAL POWER METAL STRIP RESISTOR - ELECTRICAL SPECIFICATION

POWER RATING (W) $P_{70\text{ }^{\circ}\text{C}}$	VALUE (Ω)	TOLERANCE (%)
8.0	0.0003	± 1.0

INTERNAL POWER METAL STRIP RESISTOR - TECHNICAL SPECIFICATION

PARAMETER	UNIT	RESISTOR CHARACTERISTICS
Component temperature coefficient (including terminal) ⁽¹⁾	ppm/K	< 35
Operating temperature range	$^{\circ}\text{C}$	-65 to 170

Note
⁽¹⁾ Component TCR - total TCR that includes the TCR effects of the resistor element and the copper terminal

INTERNAL CAPACITORS - ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	VALUE	TOLERANCE (%)	UNITS
Capacitance	C	68	± 10	nF
Voltage	V	100	-	V
Operating temperature range	T_{op}	-55 to +150	-	$^{\circ}\text{C}$

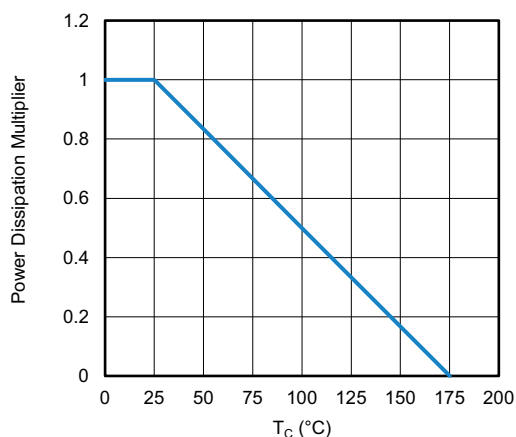


Fig. 1 - Normalized Power Dissipation

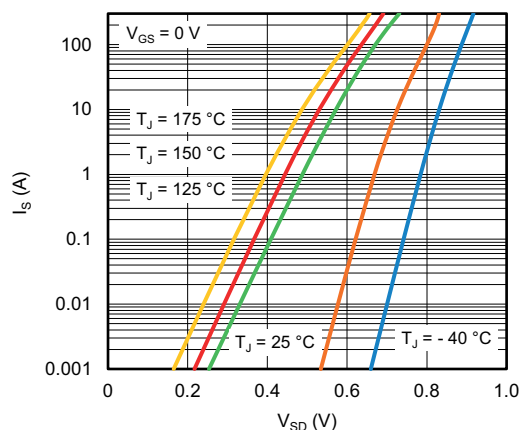


Fig. 4 - Typical Body Diode Source-to-Drain Current Characteristics

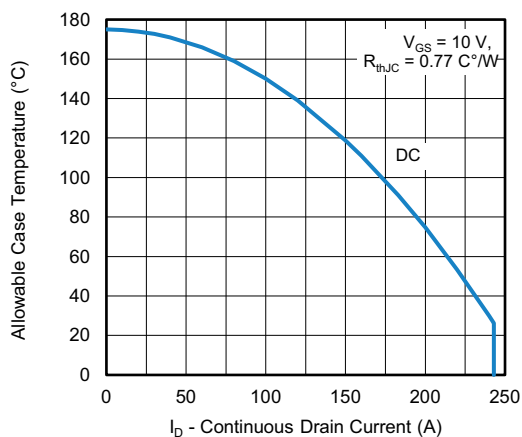


Fig. 2 - Maximum Continuous Drain Current vs. Case Temperature

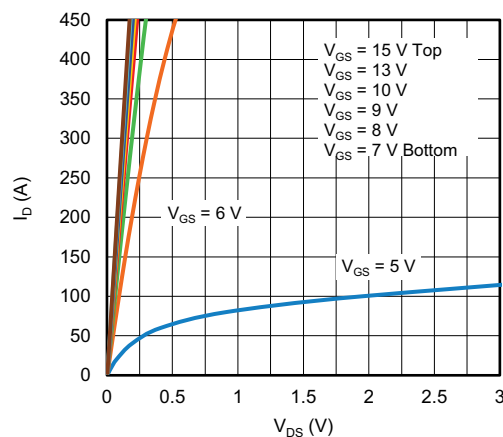
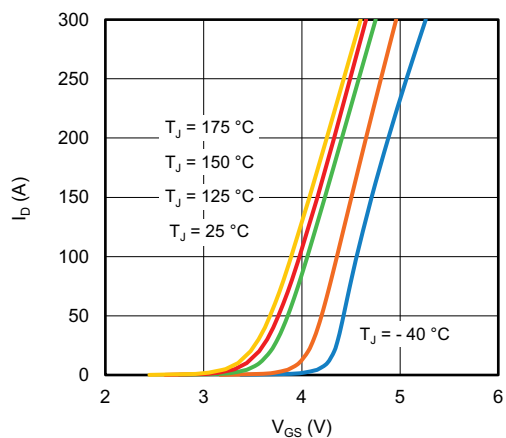
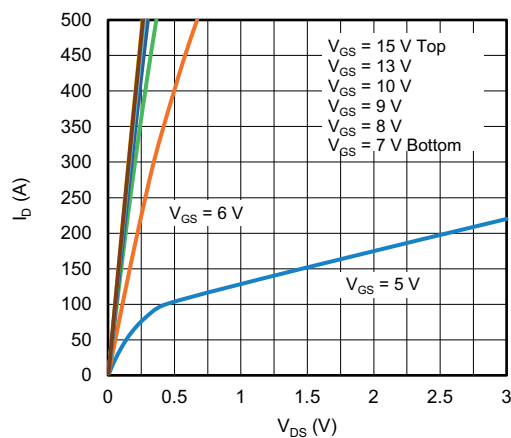

Fig. 5 - Typical Drain to Source Current Output Characteristics at $T_J = -40^\circ\text{C}$


Fig. 3 - Typical Transfer Characteristics


Fig. 6 - Typical Drain to Source Current Output Characteristics at $T_J = 25^\circ\text{C}$

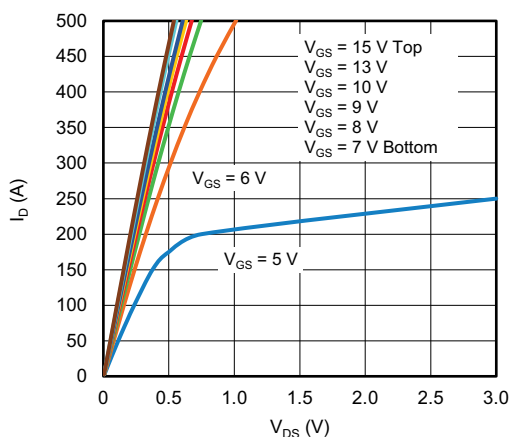


Fig. 7 - Typical Drain to Source Current Output Characteristics at $T_J = 175\text{ }^{\circ}\text{C}$

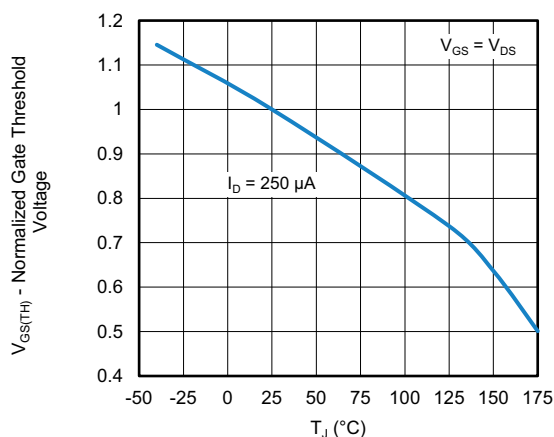


Fig. 10 - Normalized Gate Threshold Voltage vs. Temperature

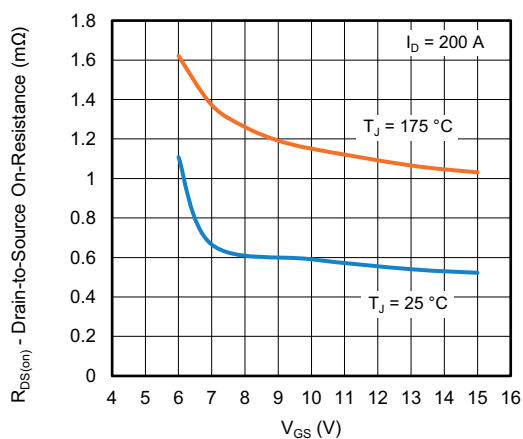


Fig. 8 - Typical Drain-to-Source On-Resistance vs. Gate to Source Voltage

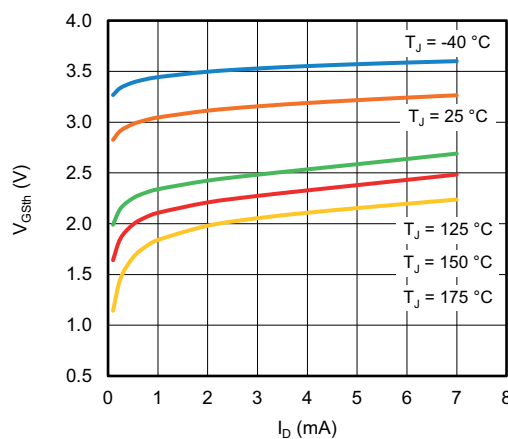


Fig. 11 - Typical Gate Threshold Voltage Characteristics

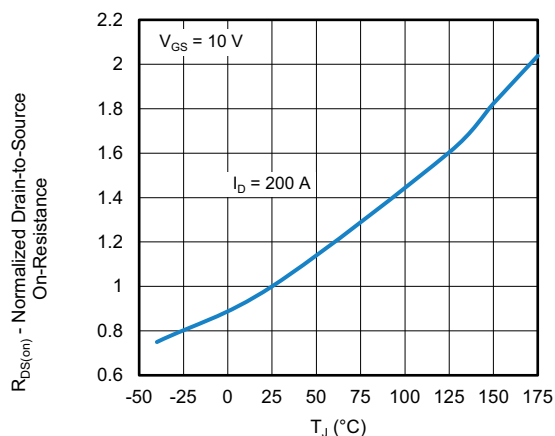


Fig. 9 - Normalized Drain-to-Source On-Resistance vs. Temperature

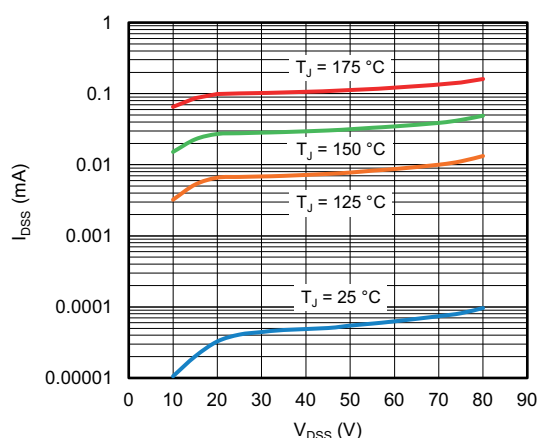


Fig. 12 - Typical Zero Gate Voltage Drain Current

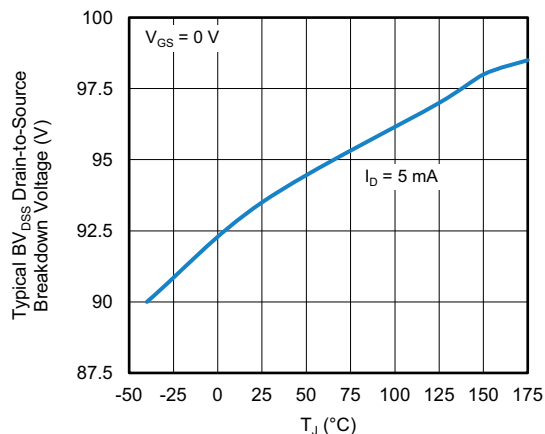


Fig. 13 - Typical Drain to Source Breakdown Voltage vs. Temperature

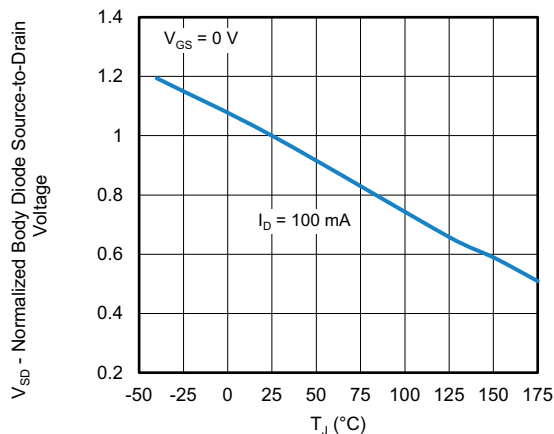


Fig. 16 - Normalized Body Diode Source-to-Drain vs. Temperature

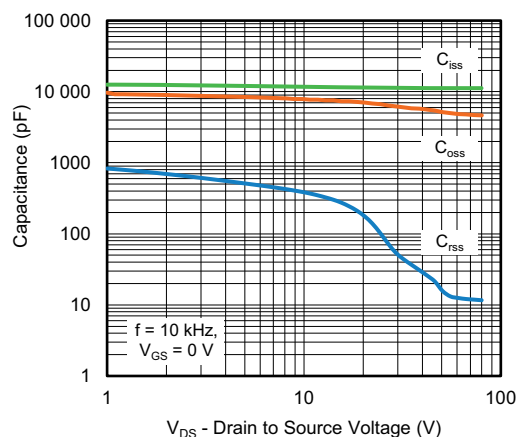


Fig. 14 - Capacitance vs. Drain-to-Source Voltage

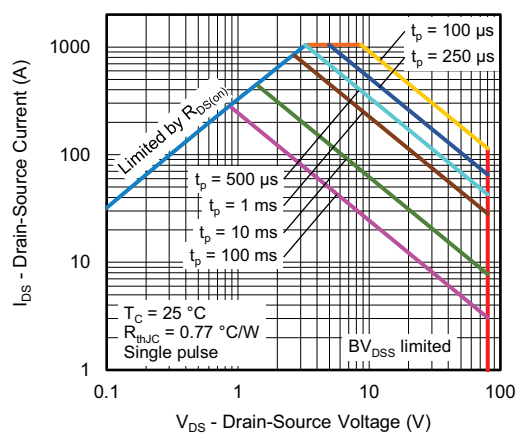


Fig. 17 - Safe Operating Area

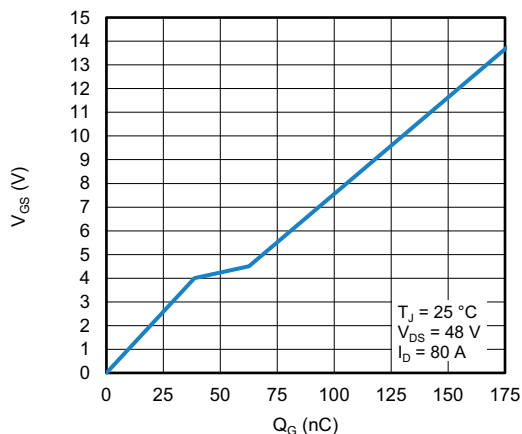


Fig. 15 - Capacitance vs. Drain-to-Source Voltage

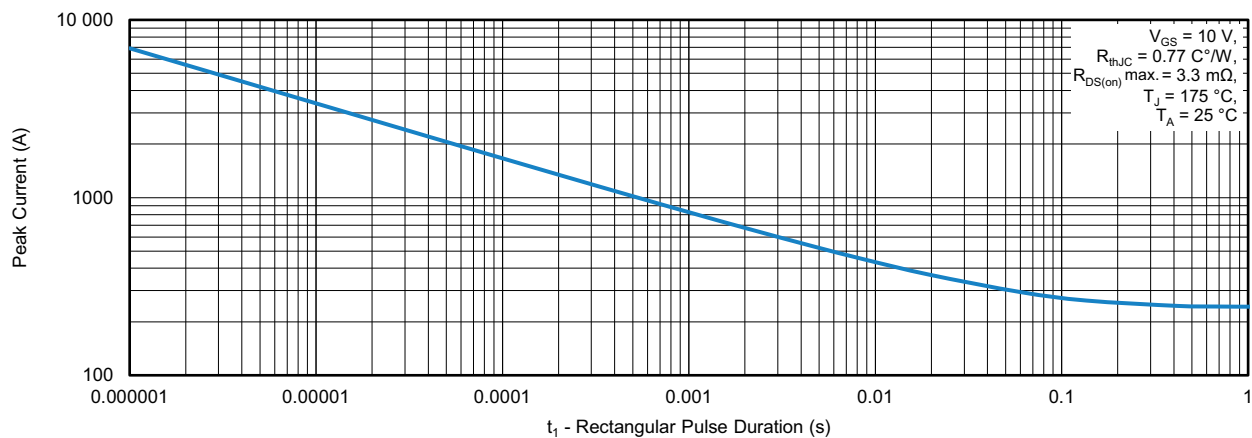


Fig. 18 - Peak Current Capability

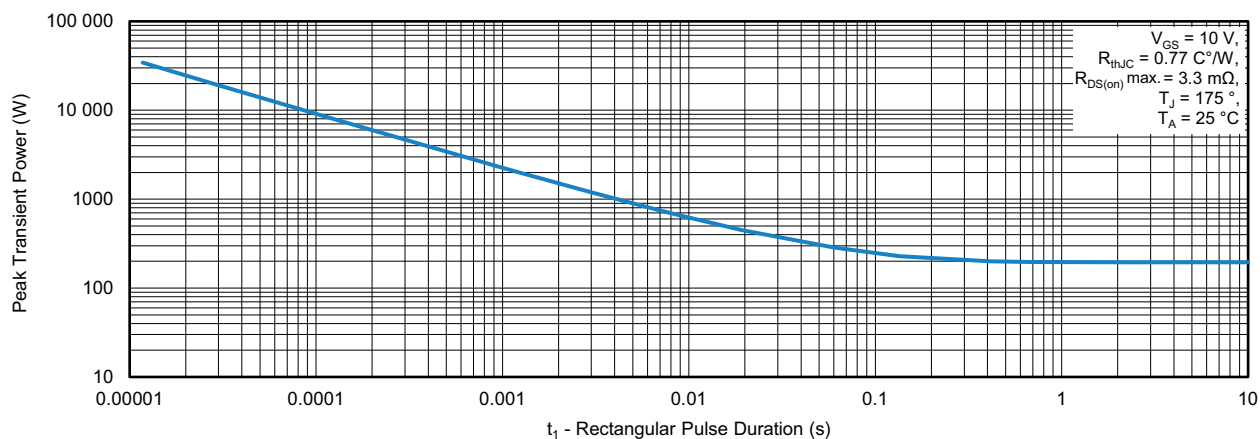


Fig. 19 - Peak Power Capability

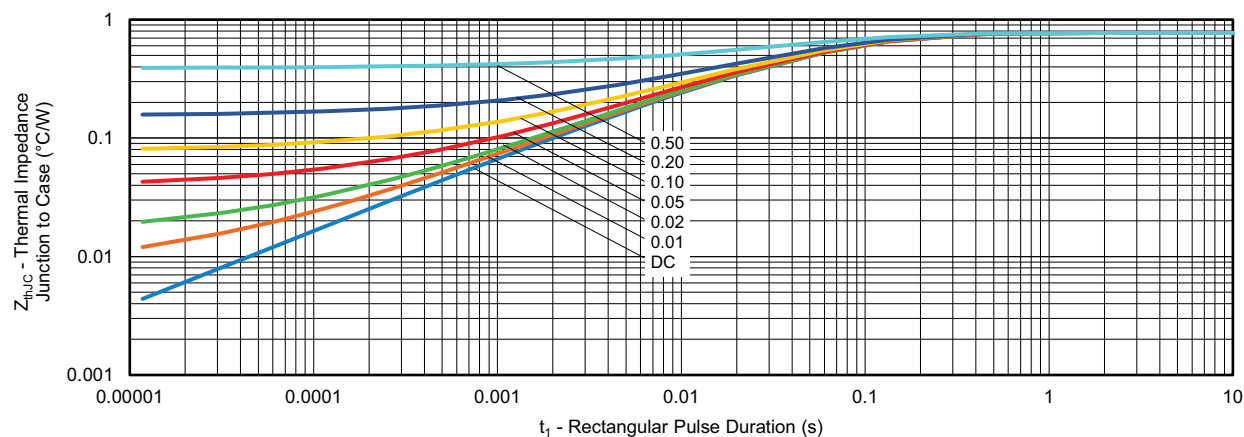


Fig. 20 - Maximum Thermal Impedance Z_{thJC} Characteristics

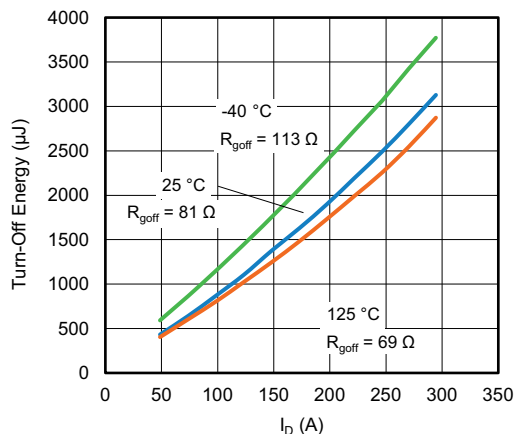


Fig. 21 - Typical Turn-Off Energy Loss vs. I_D
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$

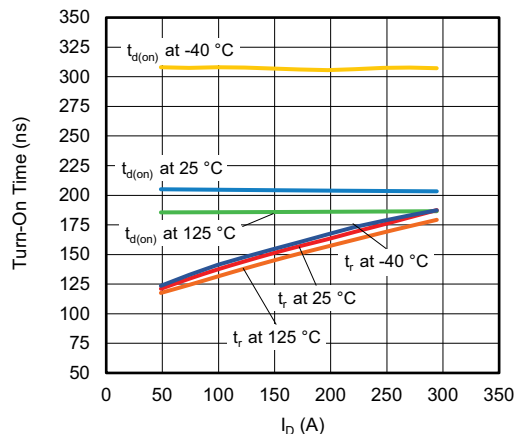


Fig. 24 - Typical Turn-On Switching Time vs. I_D
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$

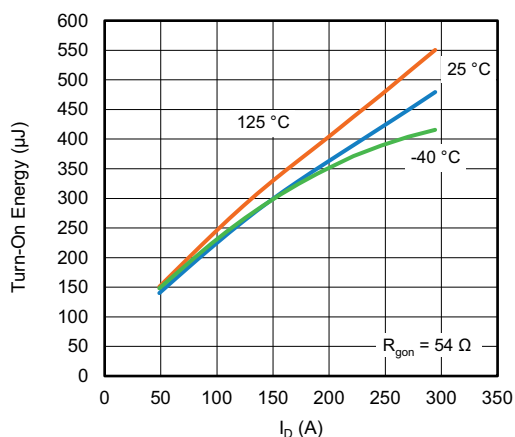


Fig. 22 - Typical Turn-On Energy Loss vs. I_D
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$

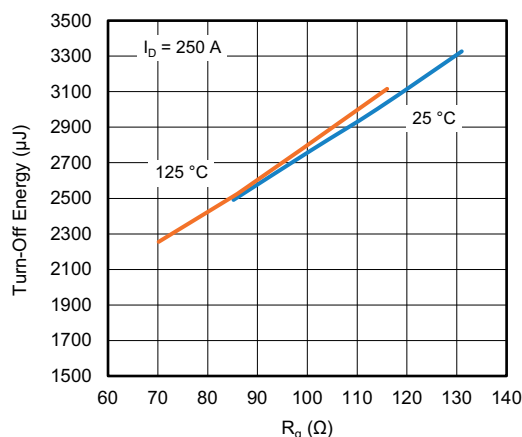


Fig. 25 - Typical Turn-Off Energy Loss vs. R_g
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$

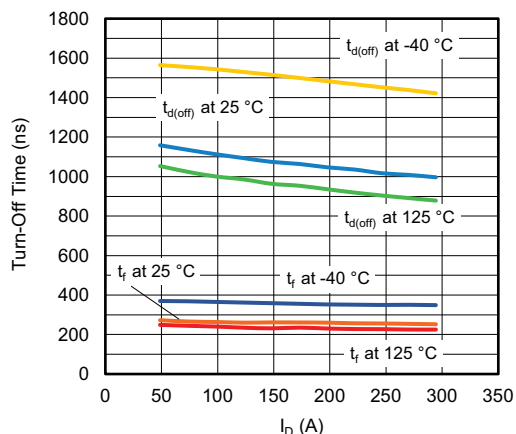


Fig. 23 - Typical Turn-Off Switching Time vs. I_D
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$

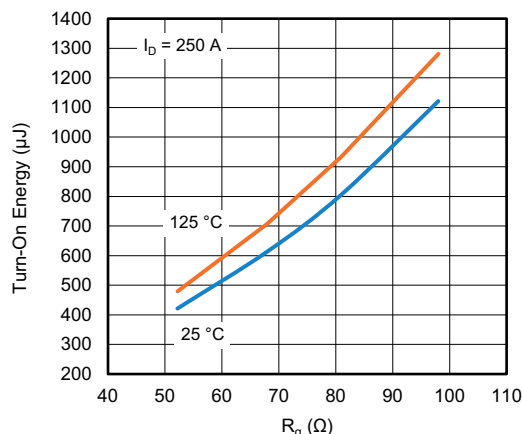
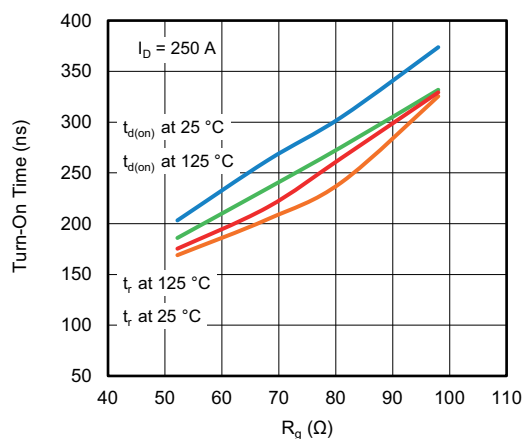
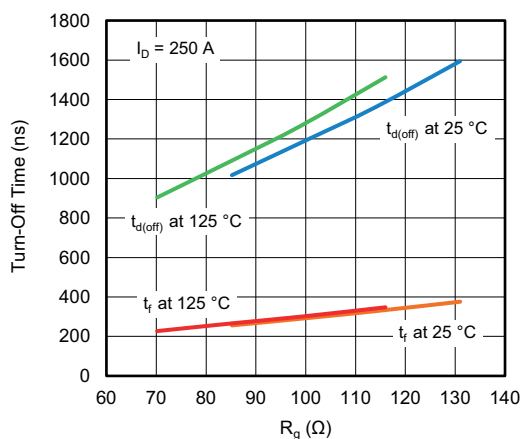


Fig. 26 - Typical Turn-On Energy Loss vs. R_g
 $V_{DD} = 52\text{ V}$, $V_{GS} = 0\text{ V} / 13\text{ V}$



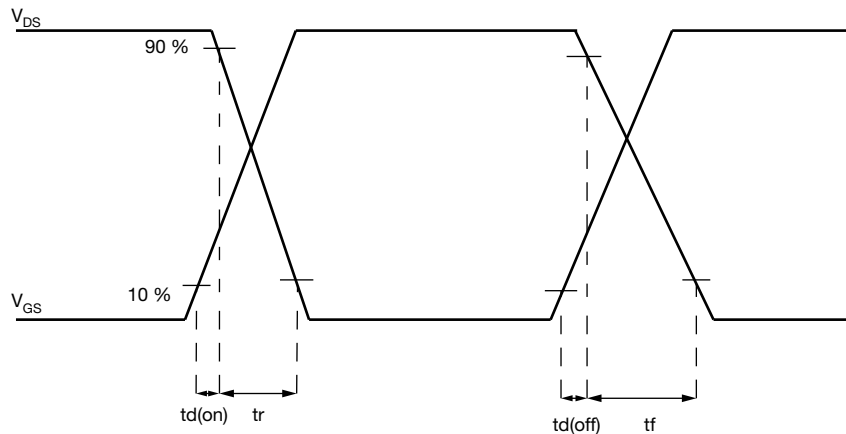
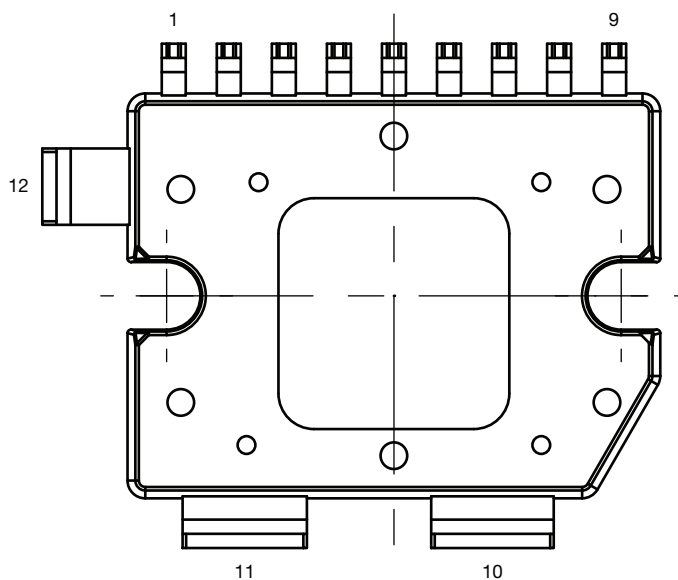
ORDERING INFORMATION TABLE

Device code

VS-	HO	T	200	C	080
1	2	3	4	5	6

- 1** - Vishay Semiconductors product
- 2** - Package indicator (HO = FlatPAK HC0)
- 3** - Circuit configuration (T = half bridge)
- 4** - Current rating (200 = 200 A)
- 5** - Switch die technology (C = PowerMOS)
- 6** - Voltage rating (080 = 80 V)

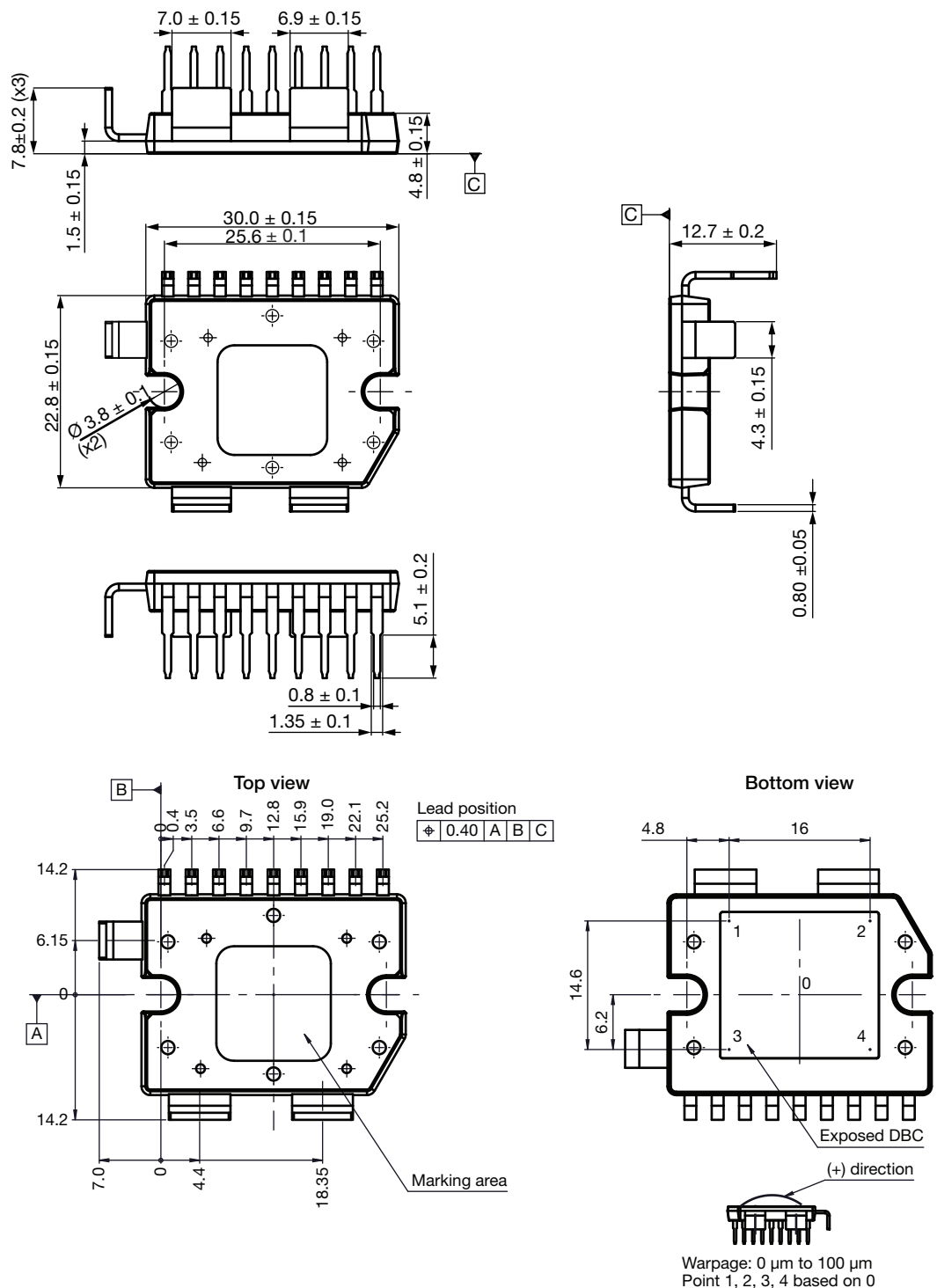
CIRCUIT CONFIGURATION		
CIRCUIT	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Half bridge	T	

SWITCHING TIME DEFINITION

VS-HOT190C080 MODULE PIN NUMBERS


PIN TABLE		
PIN ON CIRCUIT	TERMINAL ON MODULE	PIN DESCRIPTION
G2	1	Q2 low side gate
S2	2	Q2 low side source sense
T1	3	Thermistor 1
T2	4	Thermistor 2
R-	5	Shunt -
R+	6	Shunt +
S1	7	Q1 high side source sense / Q2 low side drain sense
D1	8	Q1 high side drain sense
G1	9	Q1 high side gate
DC+	10	Q1 high side power drain
GND	11	Q2 low side power source
POUT	12	Phase out connection



DIMENSIONS in millimeters



Notes

- Finishing: tin 100 % matt plating 8 µm to 20 µm all over the lead-frame terminals, only except for dumbbar cut sections
- Tin plating solderability / wettability criteria as per specification J-STD-002E



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